

IN THE CLAIMS:

Please **rewrite claims 1, 6, 9, and 14** as follows:

Sub
B1

a6

1. (Amended) A liquid crystal display device comprising:

upper and lower substrates with a liquid crystal layer interposed therebetween;

a sealant between the upper and lower substrates in an area near an edge of the upper substrate;

a plurality of source and gate pads on the lower substrate;

a plurality of gate and data lines on the lower substrate, each gate line being electrically connected with the corresponding gate pad, each data line being electrically connected with the corresponding source pad;

a gate insulating layer between the gate lines and the data lines;

a source PCB and a gate PCB electrically connected with the plurality of source pads and the plurality of gate pads, respectively, the source PCB and the gate PCB being formed outside the area in which the sealant is formed such that the upper substrate is not formed over the source PCB or the gate PCB;

and

a plurality of transmitting wires on the lower substrate, the transmitting wires being electrically connected with the gate and source pads across the sealant such that the source PCB is electrically connected with the gate PCB.

6. (Amended) A liquid crystal display device, comprising:

upper and lower substrates with a liquid crystal layer interposed therebetween;

a sealant between the upper and lower substrates;

a plurality of source and gate pads on the lower substrate;

a plurality of gate and data lines on the lower substrate, each gate line being electrically connected with the corresponding gate pad, each data line being electrically connected with the corresponding source pad;

a gate insulating layer between the gate lines and the data lines;

a source PCB electrically connected with the plurality of source pads;

a gate PCB electrically connected with the plurality of gate pads;

a plurality of transmitting wires on the lower substrate, the transmitting wires being electrically connected with the gate and source pads across the sealant such that the source PCB is electrically connected with the gate PCB; and

a repair wire crossing with each gate transmitting wire with the gate insulating layer interposed between the repair wire and the gate transmitting wire, wherein a specific resistance of the repair wire is below $10\mu\Omega/\text{cm}$ inclusive.

9. (Amended) A liquid crystal display device, comprising:

upper and lower substrates with a liquid crystal layer interposed therebetween;

B1
98
cont

a sealant between the upper and lower substrates;
a plurality of source and gate pads on the lower substrate;
a plurality of gate and data lines on the lower substrate, each gate line being electrically connected with the corresponding gate pad, each data line being electrically connected with the corresponding source pad;
a gate insulating layer between the gate lines and the data lines;
a source PCB electrically connected with the plurality of source pads;
a gate PCB electrically connected with the plurality of gate pads;
a plurality of transmitting wires on the lower substrate, the transmitting wires being electrically connected with the gate and source pads across the sealant such that the source PCB is electrically connected with the gate PCB; and
a repair wire crossing with each gate transmitting wire with the gate insulating layer interposed between the repair wire and the gate transmitting wire, wherein the repair wire includes first and second closed roofs, the first closed roof being formed along first edge of the upper substrate, the second closed roof being formed along second edge of the upper substrate.

Sub 1
99

14. (Amended) A method of fabricating a liquid crystal display device, the method comprising:
preparing first and second substrates;
forming a plurality of gate lines, gate pads, gate transmitting wires, and dummy patterns on the first substrate;

b1 forming a gate insulating layer on the gate lines, gate pads, gate transmitting wires, and dummy patterns;

forming a plurality of data lines and data pads on the gate insulating layer;

forming a passivation layer on the data lines and the data pads;

forming a sealant on the first substrate;

attaching the first and second substrates;

scribing and breaking the second substrate; and

forming a liquid crystal layer between the first and second substrates.
